

IN THE CLAIMS

1. (currently amended) A method of making a microelectronic package, comprising:

a) folding a substrate for accepting a microelectronic element having a length in a first portion, said substrate having at least one folding portion, said folding including engaging the substrate with a die having an engagement surface so that said at least one folding portion of said substrate pivots with respect to said first portion about an axis between said first portion and said folding portion, said engagement surface having a second length, such that as said engagement surface of said die engages said substrate and folds said substrate, said engagement surface extends at least substantially over the entire length of said microelectronic element to thereby cause said substrate to extend at least substantially over the entire length of the microelectronic element.

2. - 8. (cancelled)

9. (original) The method of claim 1, wherein said substrate carries a microelectronic element at a first end of said substrate and said folding portion comprises a second end, said second end of said substrate being opposite said first end.

10. (original) The method of claim 9, wherein, before said step of folding, said substrate is arranged so that said second end extends horizontally away from said microelectronic element on one side and said engagement surface engages said second end of said substrate.

11. (original) The method of claim 10, wherein said die advances toward said microelectronic element so that said second end follows said engagement surface and travels back over said microelectronic element as said die advances.

12. (original) The method of claim 10, wherein, after said step of folding, said second end is disposed on an upper side of the package.

13. (original) The method of claim 12, wherein said substrate has connection terminals at said second end and further comprising attaching a microelectronic part to said connection terminals.

14. (original) The method of claim 1, wherein said substrate comprises mounting terminals and connection terminals.

15. (original) The method of claim 14, wherein said mounting terminals are formed in a mounting portion of said substrate for mounting the microelectronic package with other elements and said connection terminals are formed in said folding portion of said substrate.

16. (original) The method of claim 15, wherein said mounting portion is coextensive with said first portion.

17. (original) The method of claim 1, wherein said substrate carries a microelectronic element in said first portion of said substrate.

18. (original) The method of claim 17, wherein said substrate is engaged by said die so that said substrate moves into a position overlying said microelectronic element.

19. (original) The method of claim 17, wherein said substrate includes mounting terminals and connection terminals exposed at an external surface of said substrate.

20. (original) The method of claim 19, wherein said step of folding is performed so that said external surface in said folding portion faces upwardly, at an upper end of the microelectronic package.

21. (original) The method of claim 20, further comprising connecting a further microelectronic part to said connection terminals.

22. (original) The method of claim 21, wherein said step of folding is performed so that said external surface in the folding portion of said substrate faces downwardly, at a lower end of the microelectronic package.

23. (original) The method of claim 22, further comprising connecting a circuit panel to said mounting terminals.

24. (original) The method of claim 1, wherein said substrate includes an internal surface further comprising attaching the microelectronic element to said internal surface of said substrate.

25. (original) The method of claim 24, wherein the microelectronic element comprises a top surface and further comprising adhering said folding portion of said substrate to said top surface during or after said step of engaging.

26. (original) The method of claim 14, wherein said substrate comprises a dielectric layer with a plurality of traces connected to a plurality of connection pads.

27. (original) The method of claim 26, wherein at least some of said plurality of traces extend from said plurality of connection pads to said connection terminals and at least some of said plurality of traces extend from said plurality of connection pads to said mounting terminals.

28. (original) The method of claim 26, wherein at least some of said plurality of traces extends from said connection terminals to said mounting terminals.

29. (original) The method of claim 26, wherein said plurality of connection pads are connected to a plurality of contacts of said microelectronic element.

30. (original) The method of claim 26, further comprising providing an adhesive layer on said substrate, the adhesive layer having apertures and attaching said adhesive

layer with said dielectric layer so that said plurality of connection pads are aligned with said apertures.

31. (original) The method of claim 30, further comprising attaching said microelectronic element having a plurality of contacts to said adhesive layer so that said microelectronic element is disposed in said first portion and said plurality of contacts face away from said adhesive layer.

32. (original) The method of claim 31, further comprising attaching wire bonding wires to said plurality of contacts and to said plurality of connection pads.

33.- 37. (cancelled)

38. (original) The method of claim 1, wherein said engagement surface of said die is shaped so as to correspond to a final desired shape for the microelectronic package.

39. (original) The method of claim 1, wherein said engagement surface of said die is sized so as to determine a final desired size for the microelectronic package.

40. - 42. (cancelled)